

In the Claims

Please amend claims 13-15, 17-18, 35-42, and 44-47 as follows below.

Please add new claims 50-55 as follows below.

Please accept a marked up version of the entire set of pending claims including the amendments made herein.

Marked Up Version of Pending Claims

1 1-12. (Cancelled)

1 13. (Currently Amended) A method for assembling an electronic
2 package, comprising:

3 forming a housing which has a bond pad located on a ~~first~~
4 top surface of a bond shelf, the bond shelf having a ~~second~~ an
5 inner side surface along a thickness of the bond shelf;

6 forming a conductive strip lengthwise along the inner side
7 ~~second~~-surface of the bond shelf; and

8 removing a portion of the conductive strip along the ~~second~~
9 inner side surface of the bond shelf to form a pair of separate
10 conductive strips lengthwise along the ~~second~~ inner side surface
11 of the bond shelf.

1 14. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the conductive strip is formed by plating a conductive
4 material onto the second inner side surface of the bond shelf.

1 15. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the portion of the conductive strip is removed by
4 drilling a portion of the second inner side surface of
5 the bond shelf including the conductive strip.

1 16. (Previously Presented) The method as recited in claim 13,
2 further comprising:

3 mounting an integrated circuit to the housing and
4 connecting the integrated circuit to the bond pad.

1 17. (Currently Amended) The method as recited in claim 14,
2 wherein

3 the portion of the conductive strip is removed by
4 etching away a portion of the conductive material on
5 the second inner side surface of the bond shelf.

1 18. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the conductive strip is formed along the second surface of
4 the bond shelf by

5 masking ~~all~~ surfaces of the bond shelf except for
6 portions of the bond shelf to be plated, the ~~second inner~~
7 side surface of the bond shelf being unmasked, and
8 plating a conductive material onto the ~~second inner~~
9 side surface of the bond shelf.

1 19. (Previously Presented) The method as recited in claim 18,
2 wherein

3 the conductive material is copper, and
4 the conductive strip is further formed by plating gold
5 onto the copper.

1 20. (Previously Presented) The method as recited in claim 19,
2 wherein

3 the portion of the conductive strip is removed by
4 drilling a portion of the bond shelf.

1 21-34. (Cancelled)

1 35. (Withdrawn - Currently Amended) The method as recited in
2 claim 13, wherein

3 the forming of the conductive strip further includes

4 forming a portion of the conductive strip around onto
5 the first top surface of the bond shelf to couple to the
6 bond pad on the first top surface of the bond shelf.

1 36. (Withdrawn - Currently Amended) The method as recited in
2 claim 35, wherein

3 the portion of the conductive strip around on the
4 first top surface of the bond shelf to further anchor the
5 conductive strip to the housing.

1 37. (Withdrawn - Currently Amended) The method as recited in
2 claim 13, wherein

3 the forming of the conductive strip further includes
4 forming a portion of the conductive strip around onto
5 the first top surface of the bond shelf to form another
6 bond pad on the first top surface of the bond shelf.

1 38. (Withdrawn - Currently Amended) The method as recited in
2 claim 37, wherein

3 the portion of the conductive strip around on the
4 first top surface of the bond shelf to further anchor the
5 conductive strip to the housing.

1 39. (Currently Amended) A method for assembling an electronic
2 package, comprising:

3 forming a housing which has a bond pad located on a top
4 surface of a bond shelf, the bond shelf having an inside a side
5 surface along an edge of the bond shelf;

6 plating a conductive material along the inside side surface
7 of the bond shelf; and

8 removing a portion of the conductive material along the
9 inside side surface of the bond shelf to form a pair of separate
10 conductive strips along the inside side surface of the bond
11 shelf.

1 40. (Currently Amended) The method of claim 39, wherein
2 the portion of the conductive material is removed by
3 drilling into the edge of the bond shelf including the
4 conductive material and the inside side surface.

1 41. (Currently Amended) The method of claim 39, wherein
2 the portion of the conductive material is removed by
3 etching away a portion of the conductive material from
4 the inside side surface of the bond shelf.

1 42. (Currently Amended) The method of claim 39, wherein,
2 the plating of the conductive material onto the inside side
3 surface of the bond shelf includes

4 masking surfaces of the housing that are not to be
5 plated and

6 leaving surfaces of the housing unmasked that are to
7 be plated, including the inside side surface of the bond
8 shelf that is to be plated.

1 43. (Previously Presented) The method of claim 42, wherein
2 the plating of the conductive material further includes
3 plating copper onto the unmasked surfaces of the
4 housing, and
5 plating gold onto the copper.

1 44. (Currently Amended) The method of claim 39 43, wherein
2 the portion of the conductive material is removed by
3 drilling into the edge of the bond shelf including the
4 conductive material and the inside side surface.

1 45. (Withdrawn - Currently Amended) The method of claim 39,
2 wherein

3 the plating of the conductive material further includes
4 plating a portion of the conductive material from the
5 inside side surface around onto the top surface of the bond
6 shelf to couple to the bond pad on the top surface of the
7 bond shelf.

1 46. (Withdrawn - Currently Amended) The method of claim 45,
2 wherein

3 the portion of the conductive material plated around
4 onto the inside side surface of the bond shelf to further
5 anchor the conductive material to the housing.

1 47. (Withdrawn - Currently Amended) The method of claim 39,
2 wherein

3 the plating of the conductive material further includes
4 plating a portion of the conductive material from the
5 inside side surface around onto the top surface of the bond
6 shelf to form another bond pad on the top surface of the
7 bond shelf.

1 48. (Withdrawn) The method of claim 47, wherein
2 the portion of the conductive material plated around
3 onto the top surface of the bond shelf to further anchor

1 50. (New) A method for assembling an electronic package,
2 comprising:

3 forming a housing which has a plurality of bond pads
4 located on a top surface of a bond shelf, the bond shelf forming
5 a rectangular cavity wall along an inner side of the bond shelf;
6 forming a conductive strip lengthwise along the rectangular
7 cavity wall of the bond shelf; and
8 removing portions of the conductive strip along the
9 rectangular cavity wall of the bond shelf to form a plurality of
10 separate conductive strips along the rectangular cavity wall of
11 the bond shelf.

1 51. (New) The method as recited in claim 50, wherein
2 the conductive strip is formed by plating a conductive
3 material onto the rectangular cavity wall of the bond shelf.

1 52. (New) The method as recited in claim 50, wherein
2 portions of the conductive strip are removed by
3 drilling a portion of the rectangular cavity wall of
4 the bond shelf including the conductive strip.

1 53. (New) The method as recited in claim 50, further
2 comprising:

3 mounting an integrated circuit to the housing and
4 connecting the integrated circuit to at least one of the
5 plurality of bond pads.

1 54. (New) The method as recited in claim 50, wherein
2 portions of the conductive strip are removed by
3 etching away portions of the conductive material on
4 the rectangular cavity wall of the bond shelf.

1 55. (New) The method as recited in claim 50, wherein
2 the conductive strip is formed along the rectangular cavity
3 wall of the bond shelf by
4 masking surfaces of the bond shelf except for portions
5 of the bond shelf to be plated, the rectangular cavity wall
6 of the bond shelf being unmasked, and
7 plating a conductive material onto the rectangular
8 cavity wall of the bond shelf.